

NTE222 Field Effect Transistor Dual Gate N-Channel MOSFET

Absolute Maximum Ratings:

Drain-Source Voltage, V_{DS}	25V
Drain-Gate Voltage, V_{DG}	30V
Drain Current, I_D	50mA
Reverse Gate Current, I_G	-10mA
Forward Gate Current, I_{GF}	10mA
Total Device Dissipation ($T_A = +25^\circ\text{C}$), P_D	360mW
Derate Above 25°C	2.4mW/ $^\circ\text{C}$
Total Device Dissipation ($T_C = +25^\circ\text{C}$), P_D	1.2mW
Derate Above 25°C	0.8mW/ $^\circ\text{C}$
Operating Junction Temperature Range, T_J	-65° to $+175^\circ\text{C}$
Storage Temperature Range, T_{stg}	-65° to $+175^\circ\text{C}$
Lead Temperature (During Soldering), T_L	$+300^\circ\text{C}$

Electrical Characteristics: ($T_A = +25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSX}$	$I_D = 10\mu\text{A}$, $V_{G1} = V_{G2} = -5\text{V}$	25	-	-	V
Gate 1-Source Breakdown Voltage	$V_{(BR)G1SO}$	$I_{G1} = \pm 10\text{mA}$, Note 1	± 6	-	± 30	V
Gate 2-Source Breakdown Voltage	$V_{(BR)G2SO}$	$I_{G2} = \pm 10\text{mA}$, Note 1	± 6	-	± 30	V
Gate 1 Leakage Current	I_{G1SS}	$V_{G1S} = \pm 5\text{V}$, $V_{G2S} = V_{DS} = 0$	-	-	± 10	nA
Gate 2 Leakage Current	I_{G2SS}	$V_{G2S} = \pm 5\text{V}$, $V_{G1S} = V_{DS} = 0$	-	-	± 10	nA
Gate 1 to Source Cutoff Voltage	$V_{G1S(off)}$	$V_{DS} = 15\text{V}$, $V_{G2S} = 4\text{V}$, $I_D = 20\mu\text{A}$	-0.5	-	-4.0	V
Gate 2 to Source Cutoff Voltage	$V_{G2S(off)}$	$V_{DS} = 15\text{V}$, $V_{G1S} = 0\text{V}$, $I_D = 20\mu\text{A}$	-0.2	-	-4.0	V
ON Characteristics (Note 2)						
Zero-Gate-Voltage Drain Current	I_{DSS}	$V_{DS} = 15\text{V}$, $V_{G2S} = 4\text{V}$, $V_{G1S} = 0\text{V}$	6	-	30	mA
Small-Signal Characteristics						
Forward Transfer Admittance	$ Y_{fs} $	$V_{DS} = 15\text{V}$, $V_{G2S} = 4\text{V}$, $V_{G1S} = 0\text{V}$, $f = 1\text{kHz}$, Note 3	10	-	22	mmhos

- Note 1. All gated breakdown voltages are measured while the device is conducting rated gate current. This insures that the gate voltage limiting network is functioning properly.
- Note 2. Pulse Test: Pulse Width = $30\mu\text{s}$, Duty Cycle $\leq 2\%$.
- Note 3. This parameter must be measured with bias voltages applied for less than five (5) seconds to avoid overheating.

Electrical Characteristics (Cont'd): ($T_A = +25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Small-Signal Characteristics (Cont'd)						
Input Capacitance	C_{iss}	$V_{DS} = 15\text{V}, V_{G2S} = 4\text{V}, I_D = I_{DSS}, f = 1\text{MHz}$	–	3.3	–	pF
Reverse Transfer Capacitance	C_{rss}	$V_{DS} = 15\text{V}, V_{G2S} = 4\text{V}, I_D = 10\text{mA}, f = 1\text{MHz}$	0.005	–	0.03	pF
Output Capacitance	C_{oss}	$V_{DS} = 15\text{V}, V_{G2S} = 4\text{V}, I_D = I_{DSS}, f = 1\text{MHz}$	–	1.4	–	pF
Functional Characteristics						
Noise Figure	NF	$V_{DD} = 18\text{V}, V_{GG} = 7\text{V}, f = 200\text{MHz}$	–	–	3.5	dB
		$V_{DD} = 15\text{V}, V_{G2S} = 4\text{V}, I_D = 10\text{mA}, f = 200\text{MHz}$	–	–	5.0	dB
Common Source Power Gain	G_{ps}	$V_{DD} = 18\text{V}, V_{GG} = 7\text{V}, f = 200\text{MHz}$	20	–	28	dB
		$V_{DD} = 15\text{V}, V_{G2S} = 4\text{V}, I_D = 10\text{mA}, f = 200\text{MHz}$	14	–	–	dB
Bandwidth	BW	$V_{DD} = 18\text{V}, V_{GG} = 7\text{V}, f = 200\text{MHz}$	7	–	12	MHz
		$V_{DD} = 18\text{V}, f_{LO} = 245\text{MHz}, f_{RF} = 200\text{MHz}, \text{Note 5}$	4	–	7	MHz
Gain Control Gate–Supply Voltage	$V_{GG(GC)}$	$V_{DD} = 18\text{V}, \Delta G_{ps} = 300\text{dB}, f = 200\text{MHz}, \text{Note 4}$	0	–	–2.0	V

Note 4. ΔG_{ps} is defined as the change in G_{ps} from the value at $V_{GG} = 7\text{V}$.

Note 5. Amplitude at input from local oscillator is 3V RMS.

